

VinMin = 11.0V VinMax = 16.0V Vout = 5.0V Iout = 2.0A Device = TPS563200DDCR Topology = Buck Created = 7/30/15 1:22:28 AM BOM Cost = \$1.18 Total Pd = 0.65W Footprint = 126.0 mm<sup>2</sup> BOM Count = 7 tSim Id = 1

# WEBENCH <sup>®</sup> Thermal Simulation Report

Design: 4368542/5 TPS563200DDCR TPS563200DDCR 11.0V-16.0V to 5.00V @ 2.0A

### **Operating Condition**

Name	Value		
VIN_OP	16.0V		
IOUT_OP	2.0A		

## **Ambient Temperature**

Name	Temperature				
Ambient_plus_Z	30.0				
Ambient_minus_Z	30.0				

#### Air Flow

Name	Direction
Flow_Type	Convection
Flow_Rate	0.0LFM
Flow Direction	Top to Bottom

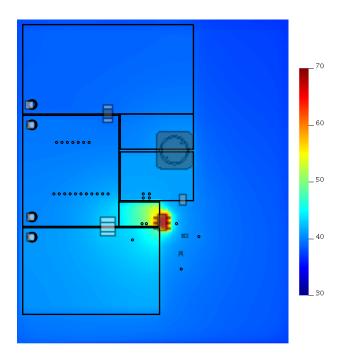
### **Edge Temperature**

Name	Temperature	Thermal Type	Thermal Type			
Edge_plus_X (Right)		Insulated				
Edge_minus_X (Left)		Insulated				
Edge_plus_Y (Top)		Insulated				
Edge_minus_Y (Bottom)		Insulated				

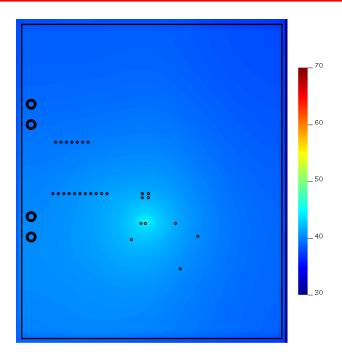
#### **BOM**

Component Name(s)	Part Number	Max Temp	Power Dissipation	Manufacture	Properties	Qty	Price	Footprint
pcb_bottom		45°C						
L1	SRR6038-3R3Y	41°C	0.083W	Bourns	L=3.3E-6H DCR=0.02Ohm	1	\$0.26	SRR6038 77.44 mm <sup>2</sup>
Cin	GRM32ER61E226KE15L	43°C	0.002W	MuRata	VDC=25.0V ESR=0.002Ohm IRMS=3.67A Cap=2.2E-5F	1	\$0.16	1210 14.7 mm <sup>2</sup>
Cout	GRM31CR61A476KE15L	39°C	0.001W	MuRata	VDC=10.0V ESR=0.01Ohm IRMS=0.0A Cap=4.7E-5F	1	\$0.21	1206 10.92 mm <sup>2</sup>
U1	TPS563200DDCR	67°C		Texas Instruments		1	\$0.52	<b>#</b>
								DDC0006A 10.468 mm <sup>2</sup>
pcb_top		66°C						

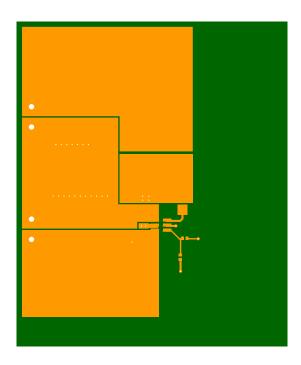
# Thermal Images



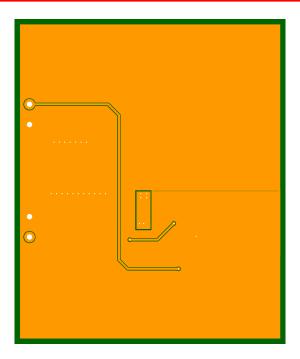
Thermal Top Image



Thermal Bottom Image

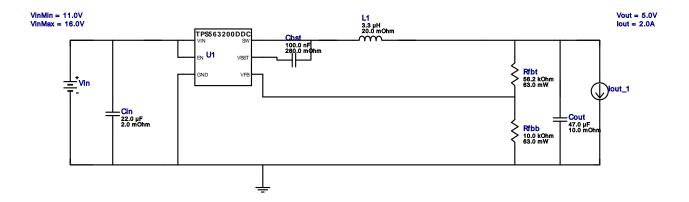


PCB Top Image



PCB Bottom Image

#### Schematic



#### Design Assistance

1. TPS563200 Product Folder: http://www.ti.com/product/TPS563200: contains the data sheet and other resources.

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